

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Part Number: XMMR18A

18mm (0.7 ") SINGLE COLOR DOT MATRIX DISPLAY

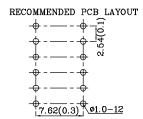


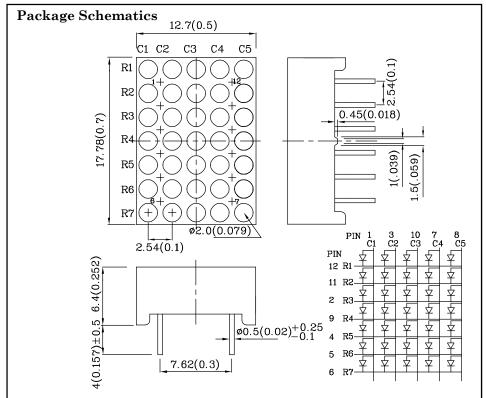
Features

- Low power consumption
- ullet Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white dots
- \bullet Optional black face provides superior color contrast
- RoHS Compliant









Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T_A =25°C)	MR (GaAlAs)	Unit		
Reverse Voltage		5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	155	mA	
Power Dissipation	P_D	75	mW	
Operating Temperature	T_{A}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

Operating Characteristics (T _A =25°C)	MR (GaAlAs)	Unit	
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	1.8	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λΡ	655*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λD	640*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	20	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	45	pF

Part Number	Emitting Color	Emitting Material	Luminous CIE127 (I _F =10m	-2007*	Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XMMR18A	Red	GaAlAs	14000 3600*	33990 8390*	655*	Column Anode

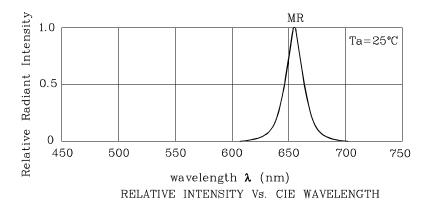
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Mar 04,2014

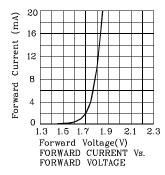
Part Number: XMMR18A

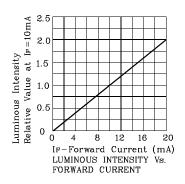
18mm (0.7 ") SINGLE COLOR DOT MATRIX DISPLAY

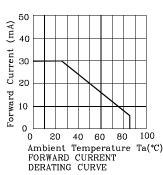


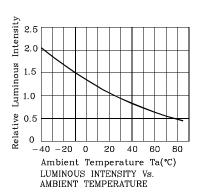


❖ MR

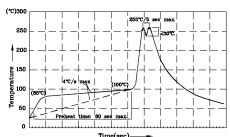








Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- nmend pre-heat temperature of 105°C or less (as measured with a noccouple attached to the LED pins) prior to immersion in the solder with a maximum solder bath temperature of 250°C wave soldering temperature between 245°C \sim 255°C for 3 sec (5 sec
- 2.Peak wave soldering temperature oetwermax).
 3.Do not apply stress to the epoxy resin (-Pixtures should not incur stress on the during soldering process.
 5.SAC 305 solder alloy is recommended.
 6.No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

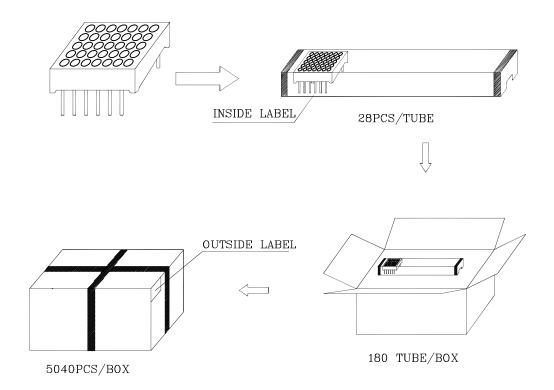
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

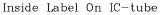
Note: Accuracy may depend on the sorting parameters.

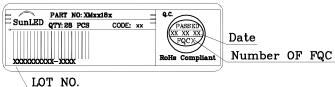
18mm (0.7 ") SINGLE COLOR DOT MATRIX DISPLAY



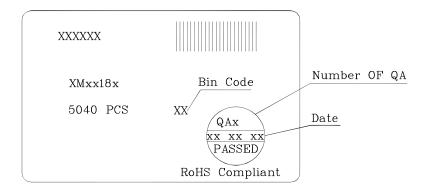
PACKING & LABEL SPECIFICATIONS







Outside Label On Box



TERMS OF USE

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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

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